



The Evolution of Payment Specifications and Tokenization

Smart Card Alliance and EMVCo Webinar October 1, 2015

Presenters and Agenda





U.S. Market Progress

- Randy Vanderhoof
- Executive Director
- Smart Card Alliance & EMV Migration Forum
- EMVCo: Mission, Structure, Activities and Industry Engagement
 - Brian Byrne
 - Director of Operations
 - EMVCo

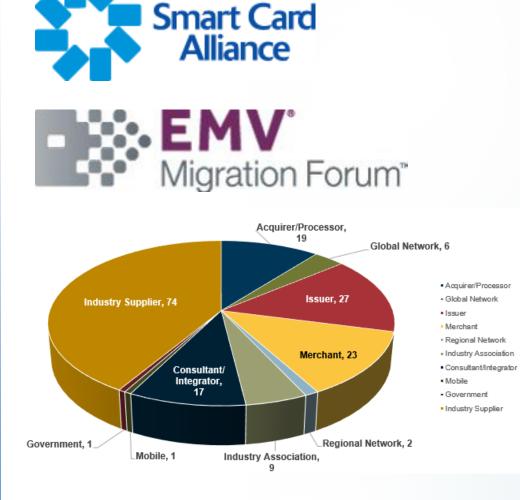




Progress for the U.S. Market in Adopting EMV Chip Payments, Contactless Mobile Payments and Payment Tokenization

Randy Vanderhoof Executive Director

Role of Payments Industry Associations



"to address issues that require broad cooperation and coordinationto ensure the successful adoption of EMV-enabled cards, devices, and terminals to ensure that migration in the US market is efficient, timely and effective."



EMV: Why Now? What at All?

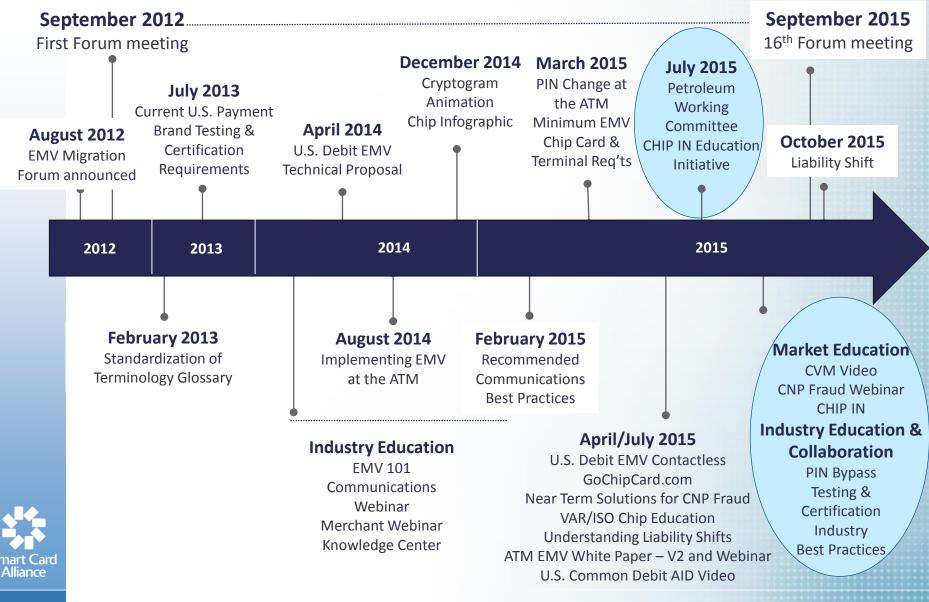
EMV migration is not just about security but also about migrating to a global standard that not only offers better security, but is the baseline for new payment products and solutions like mobile payments.

Key reasons:

- Security & fraud last major market for counterfeit cards
- Future innovation
- Global standard and interoperability
- Fewer fraud events benefit consumers and merchants
- U.S. travelers experience fewer acceptance problems when traveling internationally



EMV Migration Forum Timeline: Summarizing Major Activities



Progress in EMV Adoption in the U.S.

- ✓ Currently U.S. has 200+ million EMV cards issued
- Visa chip card issuance in the U.S. is now higher than any other country
 - 151.8 million Visa chip cards issued in the U.S. as of Sept. 15, 2015
- Estimated 314,000 merchant locations are now accepting EMV chip transactions
 - SMB retailers account for 50% of Visa's chip payment volume
- Largest retailers report significant number of chip-on-chip transactions
- ✓ Payments Security Task Force estimates that about 40 percent of terminals will be capable of accepting chip cards by the end of 2015



Resources from the EMV Migration Forum

EMV Resources on www.EMV-Connection.com

- Web: GoChipCard.Com
- Marketing: CHIP IN campaign
- Video: EMV video b-roll
- White Paper: "Understanding the 2015 U.S. Fraud Liability Shifts"
- White Paper: "Near-Term Solutions to Address the Growing Threat of CNP Fraud"
- Technical Guidance: US Debit Technical Proposal
- Webinar: Implementing EMV at the ATM July 14, 2015











EMVCo Global Payment Specifications

Brian Byrne, EMVCo Director of Operations Webinar, October 1, 2015

Semvco Agenda

EMVCo

- History, Mission and Scope
- Structure

EMVCo's Activities

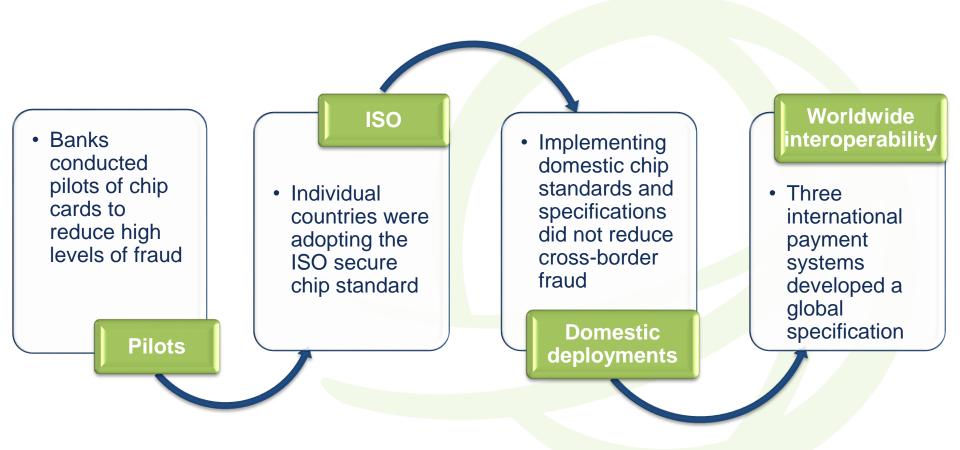
- Contact and Contactless Chip Specifications for Card and Mobile Payments
- Type Approval Terminals, Chip Security, Mobile Handsets
- The Next Generation of EMV Chip Specifications
- Payment Tokenisation
- 3D Secure 2.0

Industry Engagement



History, Mission and Scope

EMVCO EMV Chip Facilitates Global Interoperability



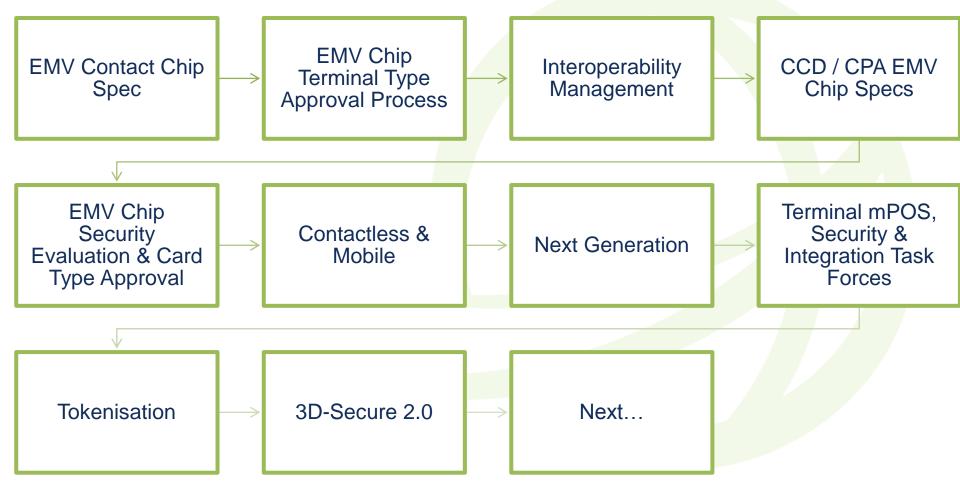


To facilitate the worldwide interoperability and acceptance of secure payment transactions by managing and evolving the EMV Specifications and related testing processes



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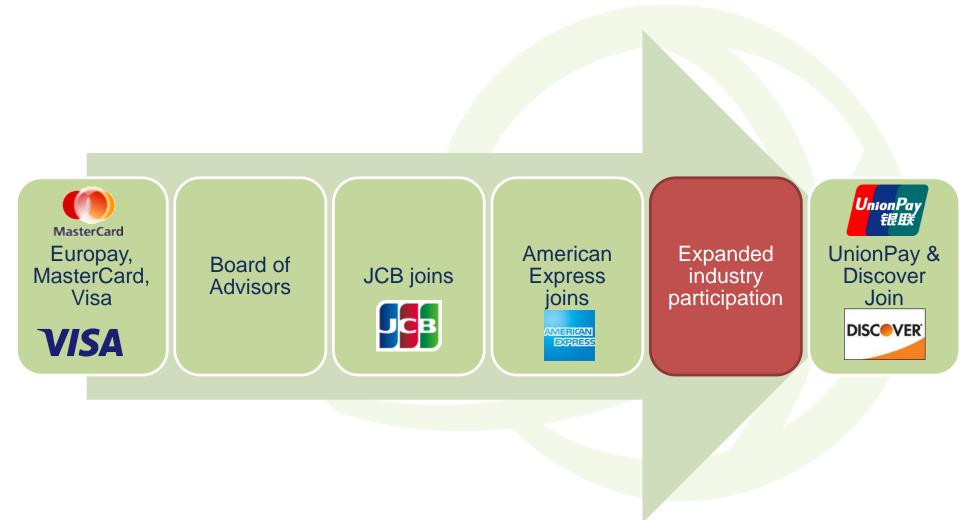
Scope



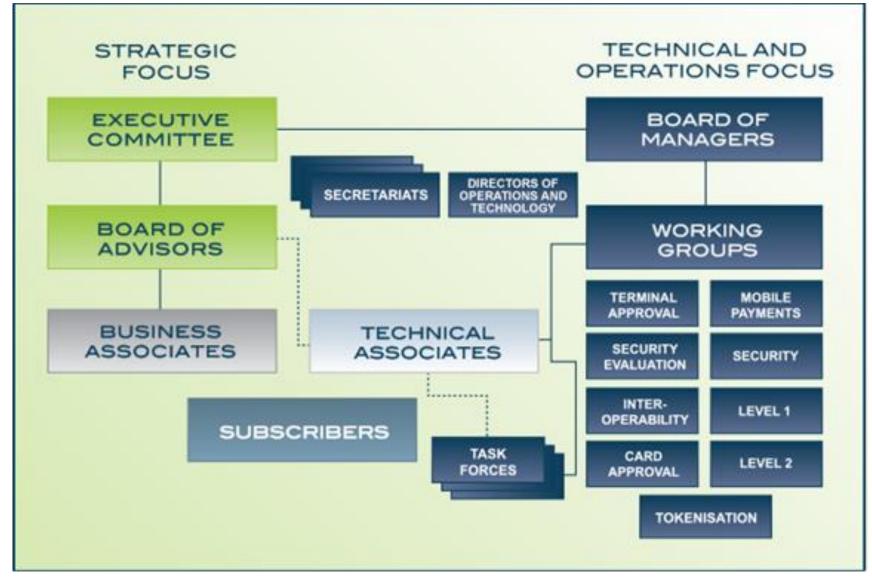


Structure

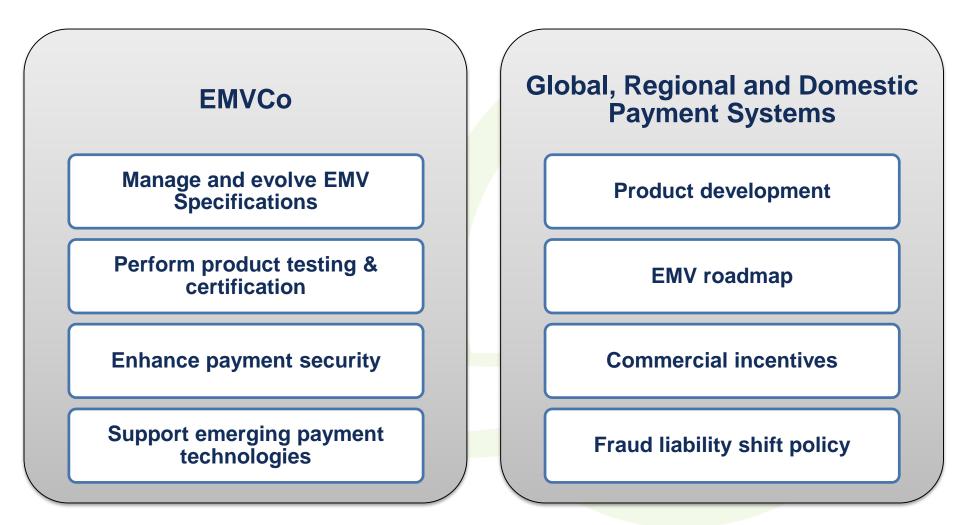
DEMVCO Participation



EMVCO EMVCo Structure 2015



EMVCO Roles of EMVCo and Payment Systems





Activities



Contact and Contactless Chip Specifications for Card and Mobile Payments

Semvco Contact EMV Payments

Contact EMV Features		
Transaction Initiation	Chip Card Insertion	MYBANK
Transaction Time	1 – 2 seconds	0012 7456 2390 5185
Form factors	Contact Chip on Card	
Security	EMV cryptography	
Implementation	Global Interoperability	
Specifications	EMV 4.3 Contact Chip	

EMV chip technology is both mature and evolving

Regularly updated with a focus on increased security, worldwide interoperability and acceptance. Actively engaging regional payments industry stakeholders in shaping the specifications. Security and interoperability actively addressed via bulletins and specification updates.

EMVCO Contactless EMV Payments

Contactless EMV Features		MY BANK
Transaction Initiation	Tap [2-4cm]	0012 7456 2390 5185
Transaction Time	Fast [< 500ms]	
Form factors	Multiple: Cards, Stickers, Fobs, Watches, Phones	()))
Security	Secured using the same strong cryptography as contact EMV	
Implementation	Global Interoperability	
Specifications	EMV Contactless 2.5	623



Type Approval – Terminals, Chip Security, Mobile Handsets

Semvco Testing and Approval

Terminal Type Approval

- Designed to assess whether EMV chip enabled acceptance terminals sufficiently conform to the functional requirements
- Level 1: verifies conformance to mechanical, electrical and protocol specifications
- Level 2: verifies whether the software demonstrates sufficient conformance

Card / Mobile Handset Type Approval

- Designed to assess whether the chip hardware and embedded EMV functionality sufficiently conforms to electro-mechanical and functional requirements
- Manage the type approval process for payment applications that are compliant with the EMV Common Core Definition (CCD) and Common Payment Application (CPA).
- Expanding to include Level 1 Approval for Mobile Handsets

Chip Security Evaluation

- Designed to assess whether a chip demonstrates sufficient assurance of minimum levels of security
- Including security mechanisms and protections designed to withstand known attacks

Semvco Testing and Approval

EMVCo Role

- Assess the compliance of vendor products developed to the EMV Specifications
- Terminal Type Approval
- Card Type Approval
- Chip Security Evaluation

Payment Systems Role

- · Specify the rules regarding how long approved products may be used in the field
- Host system and terminal deployment testing and approval
- Type approval process for chip cards that comply with their card application specifications
- Card functional security evaluation
- Card personalisation approval



EMV Next Generation

Semvco Next Generation Goal

To establish a single kernel for acceptance with a common, robust technology platform supporting contact and contactless / mobile interfaces for both online and offline transactions.

Future proof EMV security

Employing a layered, modular and flexible design

Simplified device design (e.g. only one offline data authentication method)

Integrated type approval process for contact and contactless

EMVCo Project Milestones

2011	Start the EMV Next Generation effort	
2012	EMVCo Next Generation scope finalisation	
2013	EMV Next Generation high-level architecture completed	
2014	EMV Next Generation proof of concept	
2015	EMV Next Generation Draft Specification completed	
2016	EMV Next Generation Specification completed	
2017	Terminal Type Approval Process availability	
2025	Payment systems may sunset the issuance of legacy contact/contactless cards	
2030	Payment systems may remove legacy cryptography (i.e. keys) from terminals	
*The timeline and milestones presented are provisional and subject to change		



Payment Tokenisation

EMVCO Overview of EMV Payment Tokens

EMV payment tokens further enhance security of digital payments and simplify purchase experience when shopping on mobile, computers or other smart devices

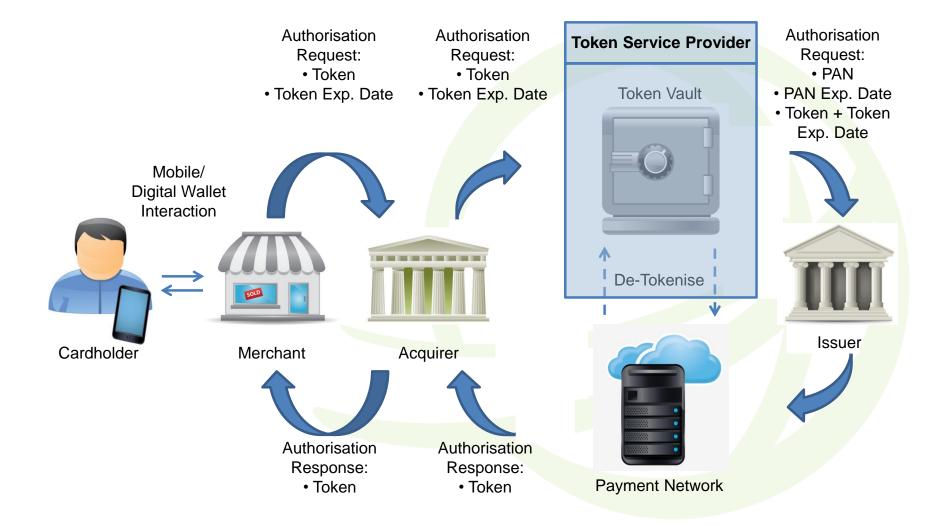
Replaces a traditional card account number with a unique payment token

Restricts the use of a payment token by device, merchant, transaction type or channel

Fraudulent activity reduced because:

Payment token is limited to a specific acceptance domain Payment token can be unlinked from card account number as required

Card account numbers are less available for compromise



EMVCO Examples of Token Activity

Broad proliferation of models (remote and proximity) has accelerated token usage:

Card-on-File Merchant

Merchant uses tokens in lieu of PANs in card-on-file database



Digital Wallet

Branded Digital Wallet presents "Pay with Wallet" in front of cardon-file



QR and Bar Code

QR or Bar Code supplier put a "barcode" in front of card-on-file



NFC

Tokens in NFC device



EMV Chip

Tokens in EMV chip device



EMVCO EMVCo Payment Tokenisation Goals

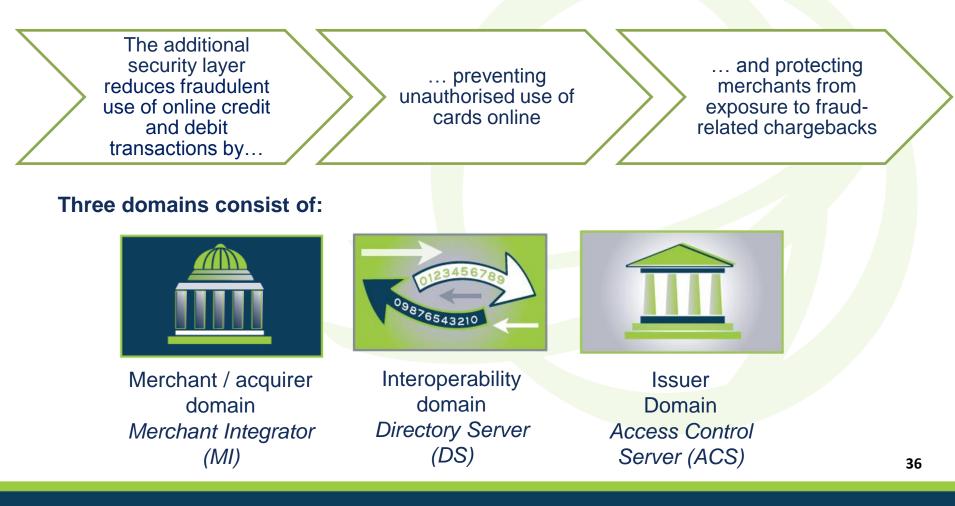
2015 Goals				
Q1-3 2015	2015 - 2016			
TSP registration & listing programme management:	Payment Tokenisation Specification – Technical Framework Updates:			
 List and registration process to be made available on the EMVCo website Ongoing work with PCI SSC for investigation of industry standard TSP security requirements 	 Clarifications – including more clarity on assurance levels and aggregator concept Payment account reference (PAR) Expanded token use cases – transit, EMV chip card offline, 3rd party TSP, ATM, split shipment receipt-less returns. 			
2015 - 2016				
 Ongoing industry engagement: Regional payments bodies Global standards bodies Merchants, processors, issuers, acquirers Payment innovators and others 	 Upcoming Tokenisation Engagement Opportunities: Oct 21, 22: Board of Advisors Boston, USA Oct 15: Seminar Barcelona, Spain Nov 3: Seminar Jakarta, Indonesia November 4th : Webinar in conjunction with SCA 			



3D Secure 2.0

EMVCO Overview of 3DS

3DS is a messaging protocol which enables consumers to directly authenticate their card with the card issuer when shopping online



EMVCO Why a New Version of the 3DS Specification is Required

Support non-browser e-commerce transactions

• In-app purchases (covers all connected device purchases)

Better integration with a merchants offering

 Enabling a smooth process for the challenge response that does not interrupt the merchant check-out experience

Facilitate a cleaner experience without sacrificing security

- Encourage frictionless authentication (where possible)
- Better use of dynamic one-time-passwords

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EMVCO Other Benefits of the New Specification



Deliver web-based service messaging to be used across multiple platforms

Offer advance intelligent risk-based decisioning





Add support for ID&V and digital wallet in addition to enriching current payment authentication flows

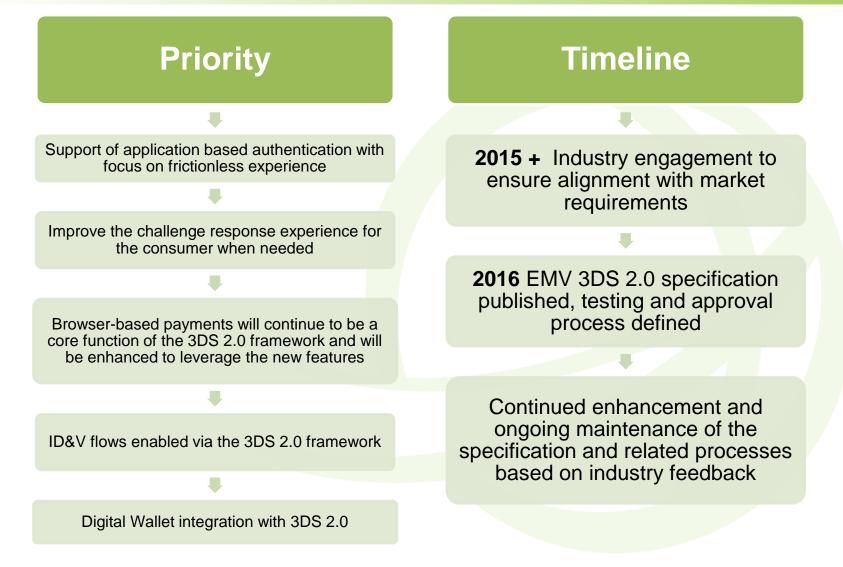
Align to country-specific and regulatory requirements



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Priorities & Planning



* The content and timeline presented is provisional and subject to change.



Industry Engagement

EMVCO Payment Community Engagement

EMVCo actively engages the payment community in shaping future specifications

Industry Engagement

EMVCo Associates

Programme

- Business Associates
- Technical Associates
- Subscriber meetings
- Partnership & liaison
 activity

Interactive Forums

- Speaking engagements
- Panels
- Seminars
- Webinars

Information Sharing

- Website
- LinkedIn
- Press releases
- Specifications
- White papers
- Other publicly available
 content

EMVCO Engagement with Global Organisations



Objective – Engage with regional and national bodies as needed to support the continued migration to EMV technology

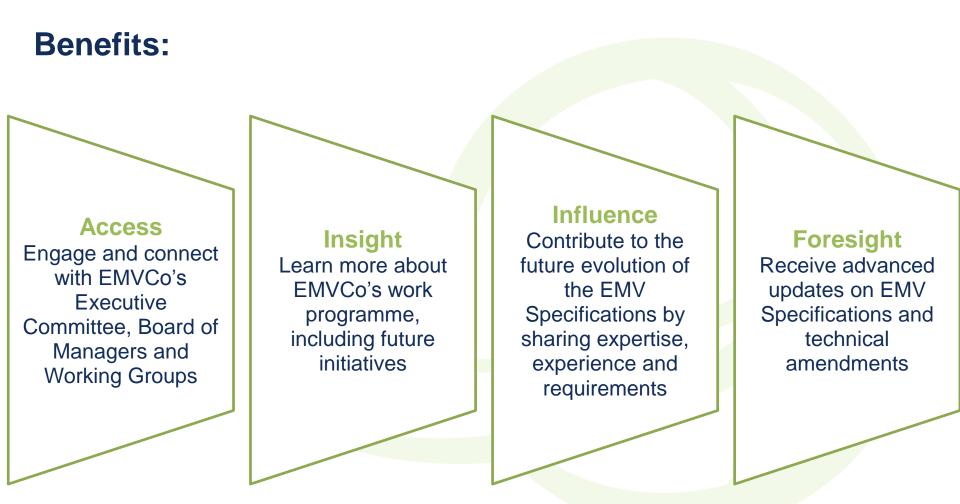


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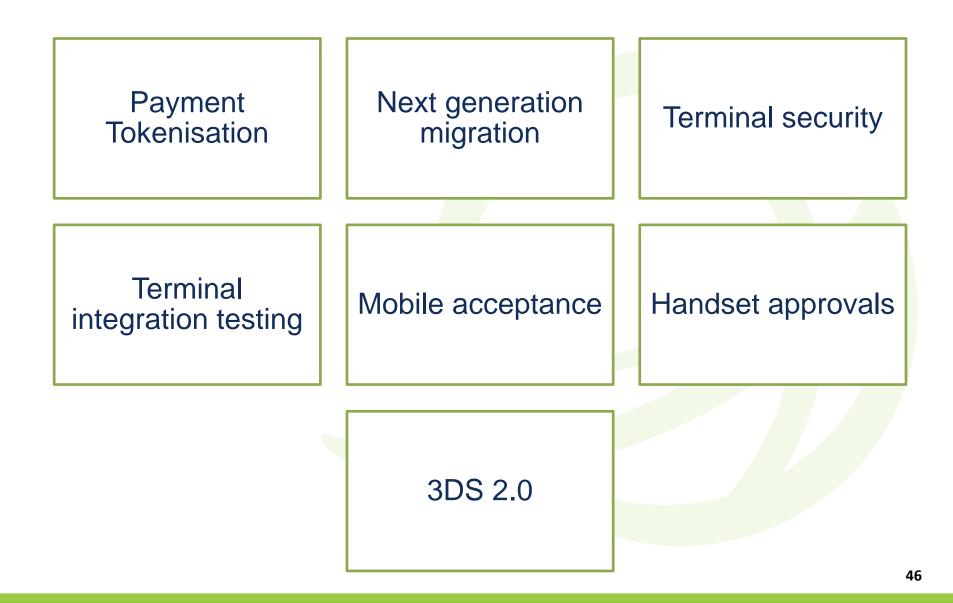


EMVCo Associates Programme (EAP)

EMVCO EAP Connects EMVCo to Industry Leaders



EMVCO Sample EMVCo Associate Engagement Topics





Summary

EMVCo serves as an industry utility to promote secure & interoperable payments worldwide by:

Actively engaging regional payments industry stakeholders in shaping the specifications

Promoting interoperability through global monitoring & specification enhancements

Providing royalty free access to specifications aligned with ISO standards

Developing underlying security mechanisms to provide robust protection within EMV environments

Continuously evaluating new payment technology developments relevant to EMVCo's scope



Thank You!

For more information visit <u>www.emvco.com</u> or join us on LinkedIn



Discover, JCB, MasterCard, UnionPay, and Visa—and supported by dozens of banks, merchants, processors, vendors and other industry stakeholders who participate as EMVCo Associates.

10 October 2014 Specification Bulletin 149: Specification Update EMV Book C-2, Version 2.4

09 October 2014

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Wrap-Up



Wrap-Up

- Next Smart Card Alliance and EMVCo Webinar: Focus on Tokenization
 - NEW date: November 4, 2015, 1:00pm ET/10:00am PT
 - Register at: <u>https://attendee.gotowebinar.com/register/9008007764697218561</u>

• Events

- EMVCo Regional Seminars: <u>https://www.emvco.com/about_emvco.aspx?id=277</u>
 - October 15, Barcelona, Spain
 - November 3, Jakarta, Indonesia
- Smart Card Alliance Payments Summit, April 5-7, 2016
 - <u>http://www.scapayments.com/</u>

• Resources

- EMVCo web site, <u>http://www.emvco.com</u>
- Smart Card Alliance web site, <u>http://www.smartcardalliance.org</u>
- EMV Connection web site, <u>http://www.emv-connection.com</u>
- GoChipCard.com web site, <u>www.gochipcard.com</u>







Q&A







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